



Orion 868

Orion 868 specification



PCB Technology	Down to 30 µm line/space
Throughput	Up to 190 sides/hour (application dependent) based on 24"x18" (610mm x 457mm) panel size
Panel Size (Maximum)	30"x24"(762mm x 610mm)
Panel Thickness Range	1 - 200mil (0.025mm – 5mm)
Panel Types and Designs	Inner and out layers; build-up and sequential lamination layer including Signal, Analog, P&G, Mixed, Cross-Shield, Laser drilled layer and other
Material Inspected	All copper foil types; Copper plating; Photo-Resist(optional); Gold plating ; Teflon and Ceramics(optional) Silver-Halide and Diazo, Alternative Oxide-Durabond
Detectable Defect Types	Open and Short-circuit, Nick, Mouse-bite, Protrusion, Pinhole, Island, Dish-down, Line/Space width violations, Annular ring violations, Extra and Missing features
Reference Source Data	CAM
Tooling	Pin-less
Operation System	Window XP™
Verification & Repair Methods	Inspectify™; Offline verification station

Dimensions	Orion 868
Height	68.5"(174cm)
Width	71.7"(182cm)
Length	68.1"(173cm)
Weight	850kg
Power	100/240 VAC; 50/60Hz; 2.5Kw

Compressed Air	6ATM, 1L/min
Temperature and Humidity	22 ± 3°C ; 50 ± 10%RH

Optional Features

CRPT/CRG	Offline reference station
Low Contrast Materials	DSTF, Double Treated and other low contrast materials
Laser Drill Inspection	Allows inspection of conformal mask and laser drill applications
PRI-Photo Resist Inspection	Allows inspection of Photo-Resist